MCR8DCM, MCR8DCN

Preferred Device

Silicon Controlled Rectifiers

Reverse Blocking Thyristors

Designed for high volume, low cost, industrial and consumer applications such as motor control; process control; temperature, light and speed control.

- Small Size
- Passivated Die for Reliability and Uniformity
- Low Level Triggering and Holding Characteristics
- Available in Surface Mount Lead Form — Case 369A
- Device Marking: Device Type, e.g., MCR8DCM, Date Code

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

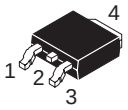
Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage(1) (T_J = –40 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open) MCR8DCM MCR8DCN	V_{DRM}, V_{RRM}	 600 800	Volts
On–State RMS Current (180° Conduction Angles; T_C = 105°C)	$I_{T(RMS)}$	8.0	Amps
Average On–State Current (180° Conduction Angles; T_C = 105°C)	$I_{T(AV)}$	5.1	Amps
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, T_J = 125°C)	I_{TSM}	80	Amps
Circuit Fusing Consideration (t = 8.3 msec)	I^2t	26	A^2sec
Forward Peak Gate Power (Pulse Width ≤ 1.0 μsec, T_C = 105°C)	P_{GM}	5.0	Watts
Forward Average Gate Power (t = 8.3 msec, T_C = 105°C)	$P_{G(AV)}$	0.5	Watts
Forward Peak Gate Current (Pulse Width ≤ 1.0 μsec, T_C = 105°C)	I_{GM}	2.0	Amps
Operating Junction Temperature Range	T_J	–40 to 125	°C
Storage Temperature Range	T_{stg}	–40 to 150	°C

(1) V_{DRM}, V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the device are exceeded.

ON Semiconductor

http://onsemi.com

SCRs
8 AMPERES RMS
600 thru 800 VOLTS



D–PAK
CASE 369A
STYLE 4

PIN ASSIGNMENT	
1	Cathode
2	Anode
3	Gate
4	Anode

ORDERING INFORMATION

Device	Package	Shipping
MCR8DCMT4	DPAK 369A	16mm Tape and Reel (2.5K/Reel)
MCR8DCNT4	DPAK 369A	16mm Tape and Reel (2.5K/Reel)

Preferred devices are recommended choices for future use and best overall value.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance — Junction to Case — Junction to Ambient — Junction to Ambient(1)	$R_{\theta JC}$ $R_{\theta JA}$ $R_{\theta JA}$	2.2 88 80	°C/W
Maximum Lead Temperature for Soldering Purposes(2)	T_L	260	°C

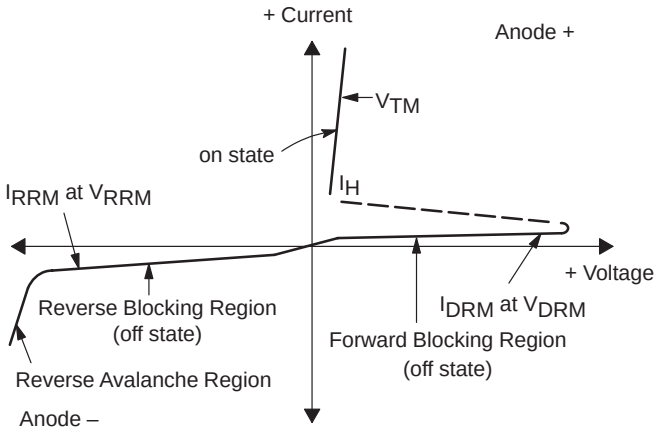
ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Characteristics	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Peak Repetitive Forward or Peak Repetitive Reverse Blocking Current (V_{AK} = Rated V_{DRM} or V_{RRM}, Gate Open) T_J = 25°C T_J = 125°C	I_{DRM}, I_{RRM}	— —	— —	0.01 5.0	mA
ON CHARACTERISTICS					
Peak On–State Voltage(3) (I_{TM} = 16 A)	V_{TM}	—	1.4	1.8	Volts
Gate Trigger Current (Continuous dc) (V_{AK} = 12 V, R_L = 100 Ω, T_J = 25°C) (T_J = –40°C)	I_{GT}	2.0 —	7.0 —	15 30	mA
Gate Trigger Voltage (Continuous dc) (V_{AK} = 12 V, R_L = 100 Ω, T_J = 25°C) (T_J = –40°C) (T_J = 125°C)	V_{GT}	0.5 — 0.2	0.65 — —	1.0 2.0 —	Volts
Holding Current (V_{AK} = 12 V, Initiating Current = 200 mA, Gate Open) T_J = 25°C T_J = –40°C	I_H	4.0 —	22 —	30 60	mA
Latching Current (V_{AK} = 12 V, I_G = 15 mA, T_J = 25°C) (V_{AK} = 12 V, I_G = 30 mA, T_J = –40°C)	I_L	4.0 —	22 —	30 60	mA
DYNAMIC CHARACTERISTICS					
Critical Rate of Rise of Off–State Voltage (V_{AK} = Rated V_{DRM}, Exponential Waveform, Gate Open, T_J = 125°C)	dv/dt	50	200	—	V/μs

(1) Surface mounted on minimum recommended pad size.
(2) 1/8″ from case for 10 seconds.
(3) Pulse Test: Pulse Width ≤ 2.0 ms, Duty Cycle ≤ 2%.

Voltage Current Characteristic of SCR

Symbol	Parameter
V_{DRM}	Peak Repetitive Off State Forward Voltage
I_{DRM}	Peak Forward Blocking Current
V_{RRM}	Peak Repetitive Off State Reverse Voltage
I_{RRM}	Peak Reverse Blocking Current
V_{TM}	Peak On State Voltage
I_H	Holding Current



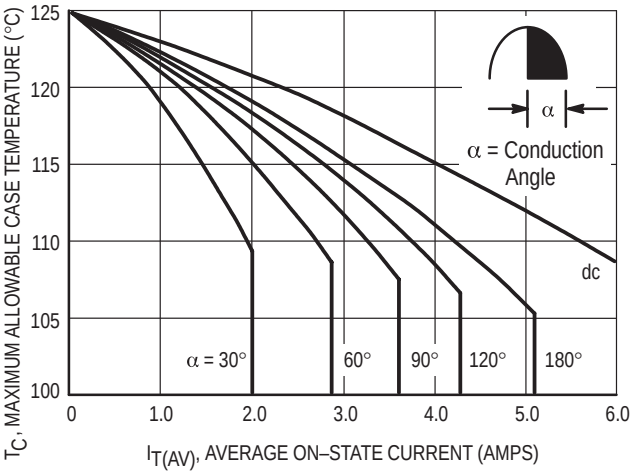


Figure 1. Average Current Derating

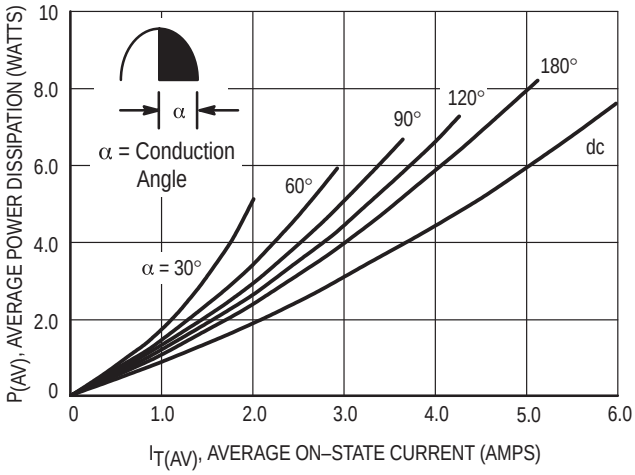


Figure 2. On–State Power Dissipation

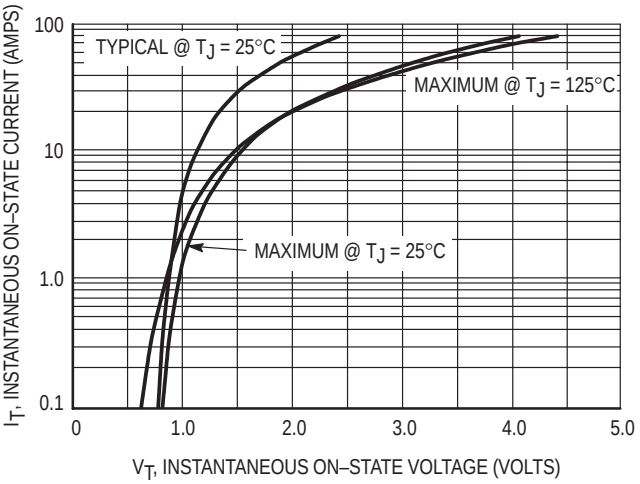


Figure 3. On–State Characteristics

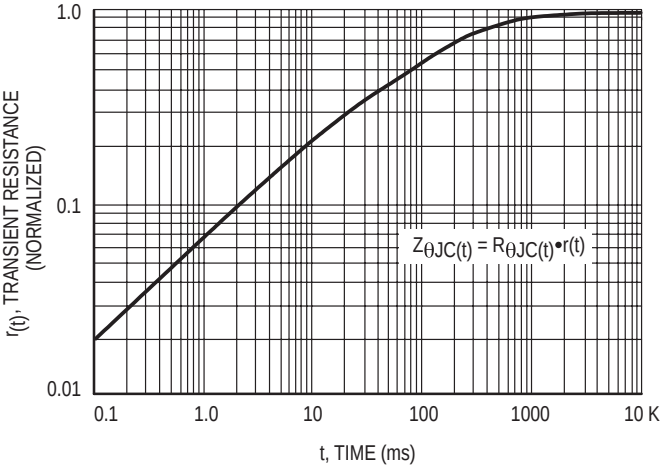


Figure 4. Transient Thermal Response

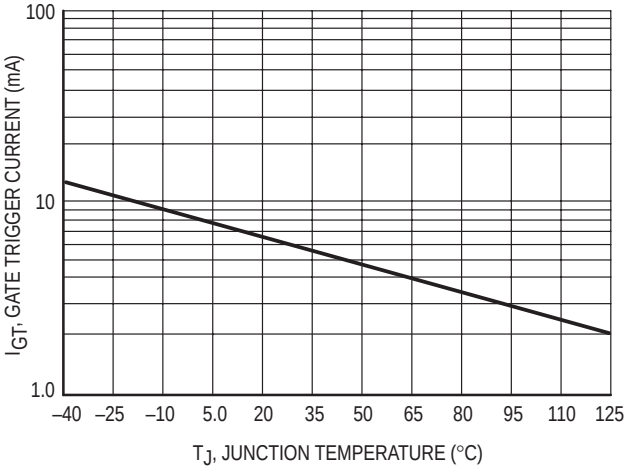


Figure 5. Typical Gate Trigger Current versus Junction Temperature

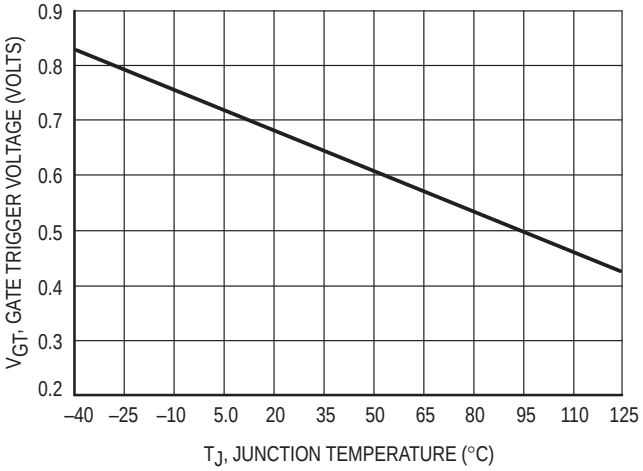


Figure 6. Typical Gate Trigger Voltage versus Junction Temperature

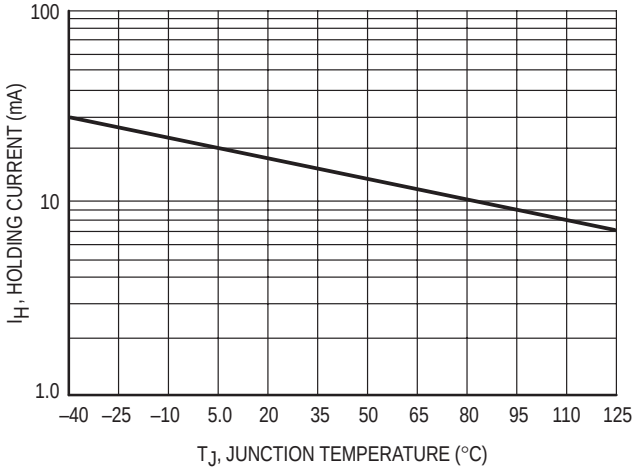


Figure 7. Typical Holding Current versus Junction Temperature

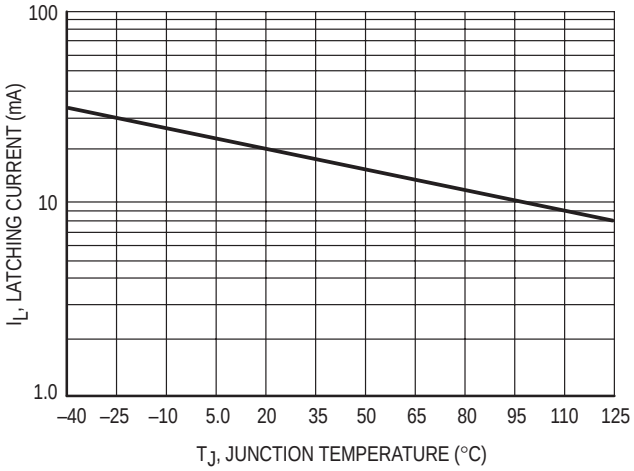


Figure 8. Typical Latching Current versus Junction Temperature

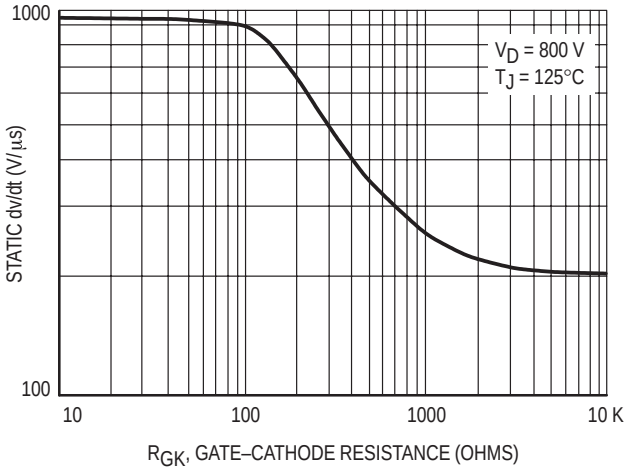
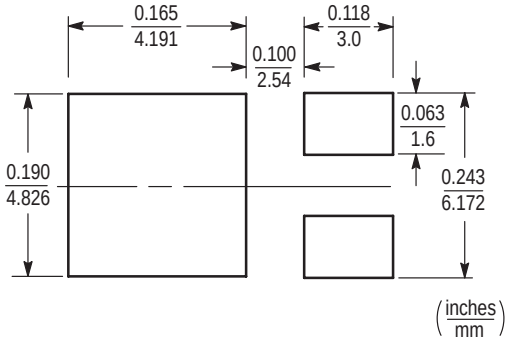


Figure 9. Exponential Static dv/dt versus Gate–Cathode Resistance

MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

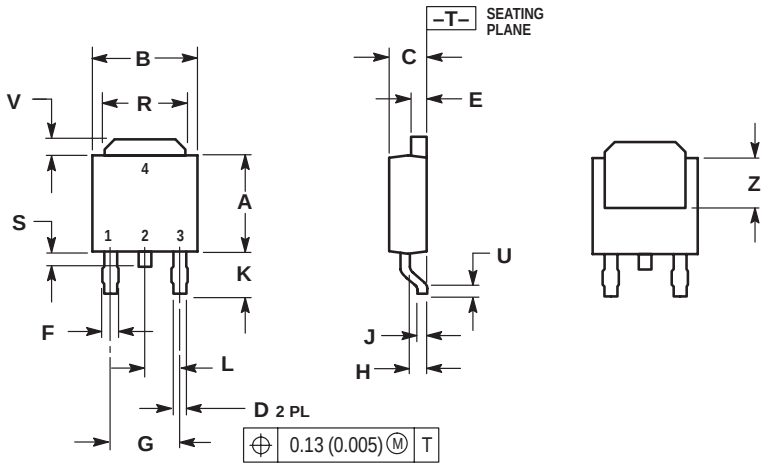
Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to insure proper solder connection interface between the board and the package. With the correct pad geometry, the packages will self align when subjected to a solder reflow process.



DPAK

PACKAGE DIMENSIONS

D–PAK
CASE 369A–13
ISSUE Z



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.235	0.250	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.180 BSC		4.58 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.175	0.215	4.45	5.46
S	0.020	0.050	0.51	1.27
U	0.020	—	0.51	—
V	0.030	0.050	0.77	1.27
Z	0.138	—	3.51	—

STYLE 4:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE

Notes

PUBLICATION ORDERING INFORMATION

NORTH AMERICA Literature Fulfillment:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada
Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada
Email: ONlit@hibbertco.com
Fax Response Line: 303–675–2167 or 800–344–3810 Toll Free USA/Canada

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

EUROPE: LDC for ON Semiconductor – European Support
German Phone: (+1) 303–308–7140 (M–F 1:00pm to 5:00pm Munich Time)
Email: ONlit–german@hibbertco.com
French Phone: (+1) 303–308–7141 (M–F 1:00pm to 5:00pm Toulouse Time)
Email: ONlit–french@hibbertco.com
English Phone: (+1) 303–308–7142 (M–F 12:00pm to 5:00pm UK Time)
Email: ONlit@hibbertco.com

EUROPEAN TOLL–FREE ACCESS*: 00–800–4422–3781
*Available from Germany, France, Italy, England, Ireland

CENTRAL/SOUTH AMERICA:
Spanish Phone: 303–308–7143 (Mon–Fri 8:00am to 5:00pm MST)
Email: ONlit–spanish@hibbertco.com

ASIA/PACIFIC: LDC for ON Semiconductor – Asia Support
Phone: 303–675–2121 (Tue–Fri 9:00am to 1:00pm, Hong Kong Time)
Toll Free from Hong Kong & Singapore:
001–800–4422–3781
Email: ONlit–asia@hibbertco.com

JAPAN: ON Semiconductor, Japan Customer Focus Center
4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–0031
Phone: 81–3–5740–2745
Email: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local
Sales Representative.